TPS382x Voltage Monitor With Watchdog Timer

1 Features

- Power-On Reset Generator With Fixed Delay Time of 200 ms (TPS3823/4/5/8) or 25 ms (TPS3820)
- Manual Reset Input (TPS3820/3/5/8)
- Reset Output Available in Active-Low (TPS3820/3/4/5), Active-High (TPS3824/5), and Open Drain (TPS3828)
- Supply Voltage Supervision Range: 2.5 V, 3 V, 3.3 V, 5 V
- Watchdog Timer (TPS3820/3/4/8)
- Supply Current of 15 µA (Typical)
- 5-Pin SOT-23 Package
- Temperature Range: −40°C to 85°C

2 Applications

- DSPs, Microcontrollers, or Microprocessors
- Industrial Equipment
- Programmable Controls
- Automotive Systems
- Portable and Battery-Powered Equipment
- Intelligent Instruments
- Wireless Communications Systems
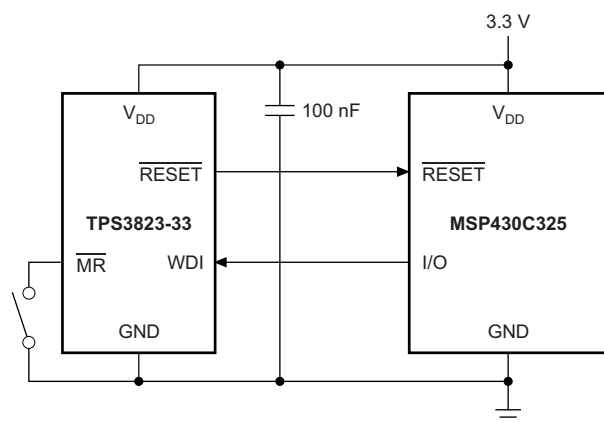- Notebook and Desktop Computers

3 Description

The TPS382x family of supervisors provide circuit initialization and timing supervision, primarily for DSP and processor-based systems. During power on, $\overline{\text{RESET}}$ asserts when the supply voltage V_{DD} becomes greater than 1.1 V. Thereafter, the supply voltage supervisor monitors V_{DD} and keeps $\overline{\text{RESET}}$ active low as long as V_{DD} remains less than the threshold voltage, V_{IT-}. An internal timer delays the return of the output to the inactive state (high) to ensure proper system reset. The delay time, t_d, starts after V_{DD} has risen above the threshold voltage (V_{IT-} + V_{HYS}). When the supply voltage drops below the threshold voltage V_{IT-}, the output becomes active (low) again. No external components are required. All the devices of this family have a fixed-sense threshold voltage, V_{IT-}, set by an internal voltage divider. The TPS382x family also offers watchdog time out options of 200 ms (TPS3820) and 1.6 s (TPS3823/4/8).
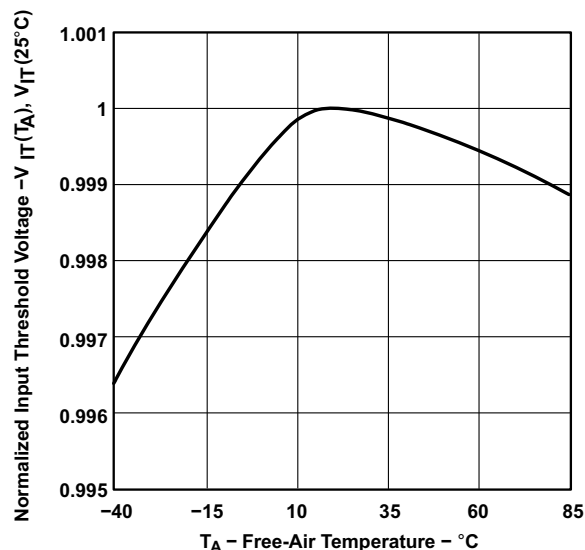
Device Information[1]

PART NUMBER	PACKAGE	BODY SIZE (NOM)
TPS382x	SOT-23 (5)	2.90 mm × 1.60 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Typical Application Schematic

Normalized Input Threshold Voltage vs Free-Air Temperature

<h1>Table of Contents</h1>

4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision J (April 2013) to Revision K   **Page**

- Added *ESD Ratings* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section 1
- Changed front-page figure... 1
- Changed *Pin Configuration and Functions* section; updated table format 4
- Changed "free-air temperature" to "junction temperature" in *Absolute Maximum Ratings* condition statement 5
- Deleted *Soldering temperature* specification from *Absolute Maximum Ratings* table.......... 5
- Changed *clamp current* to *current* specifications in *Absolute Maximum Ratings* table 5
- Changed Removed V_I from *Absolute Maximum Ratings* table 5
- Changed Removed V_{SENSE} from *Recommended Operating Conditions* table........ 5
- Changed free-air temperature to junction temperature in *Electrical Characteristics* condition statement............ 6
- Changed "T_A" to "T_J" in *Timing Requirements* condition statement 7
- Changed "T_A" to "T_J" in *Switching Characteristics* condition statement 7
- Added footnote (3) to *Functional Block Diagram* 10
- Changed part number shown in Figure 9 12
- Changed Figure 11 14

Changes from Revision I (February 2013) to Revision J   **Page**

- Added *TPS382xA-33* to second $\overline{RESET}$ row of V_{OH} parameter in *Electrical Characteristics* table 6
- Added *TPS382xA-33* to third $\overline{RESET}$ row of V_{OL} parameter in *Electrical Characteristics* table 6
- Corrected typo in V_{OL} $\overline{RESET}$ parameter test conditions........ 6
- Added *TPS382xA-33* to third and seventh rows of V_{IT-} parameter in *Electrical Characteristics* table........ 6
- Added *TPS382xA-33* to third row of V_{hys} parameter in *Electrical Characteristics* table........ 6
- Added *TPS382xA-33* to third row of I_{OS} parameter in *Electrical Characteristics* table........ 7

Changes from Revision H (July 2012) to Revision I   **Page**

5 Device Comparison Table

DEVICE	RESET	$\overline{\text{RESET}}$	WDI	$\overline{\text{MR}}$
TPS3820		Push-pull	X	X
TPS3823		Push-pull	X	X
TPS3823A		Push-pull	X	X
TPS3824	Push-pull		X	
TPS3825	Push-pull	Push-pull		X
TPS3828	Open-drain	Push-pull	X	X

6 Pin Configuration and Functions

TPS3820, TPS3823, TPS3823A, TPS3828: DBV PACKAGE
5-Pin SOT-23
Top View
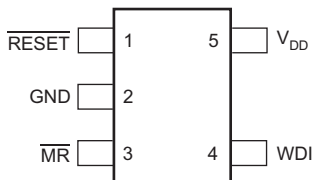
TPS3824: DBV PACKAGE
5-Pin SOT-23
Top View
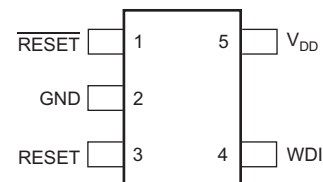
TPS3825: DBV PACKAGE
5-Pin SOT-23
Top View

Pin Functions

NAME	TPS3820, TPS3823, TPS3823A, TPS3828	TPS3824	TPS3825	I/O	DESCRIPTION
GND	2	2	2	—	Ground connection
$\overline{\text{MR}}$	3	—	4	I	Manual-reset input. Pull low to force a reset. RESET remains low as long as MR is low and for the time-out period after MR goes high. Leave unconnected or connect to V_{DD} when unused.
RESET	—	3	3	O	Active-high reset output. Either push-pull or open-drain output stage.
$\overline{\text{RESET}}$	1	1	1	O	Active-low reset output. Either push-pull or open-drain output stage.
V_{DD}	5	5	5	I	Supply voltage. Powers the device and monitors its own voltage.
WDI	4	4	—	I	Watchdog timer input. If WDI remains high or low longer than the time-out period, then reset is triggered. The timer clears when reset is asserted or when WDI sees a rising edge or a falling edge. If unused, the WDI connection must be high impedance to prevent it from causing a reset event.

7 Specifications

7.1 Absolute Maximum Ratings

over operating junction temperature range (unless otherwise noted)[1] [2]

		MIN	MAX	UNIT
Voltage	V_{DD}	−0.3	6	V
	RESET, $\overline{RESET}$, MR, WDI	−0.3	$(V_{DD} + 0.3)$	
Current	Maximum low output, I_{OL}	−5	5	mA
	Maximum high output, I_{OH}	−5	5	
	Output range ($V_O < 0$ or $V_O > V_{DD}$), I_{OK}	−10	10	
	Continuous total power dissipation	See *Thermal Information*		
Temperature	Operating free-air, T_A	−40	85	°C
	Storage, T_{stg}	−65	150	

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values are with respect to GND.

7.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins[1]	±2000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins[2]	±500	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

over operating junction temperature range (unless otherwise noted).

		MIN	NOM	MAX	UNIT
V_{DD}	Supply voltage	1.1		5.5	V
V_{IH}	High-level input voltage at $\overline{MR}$ and WDI	$0.7 \times V_{DD}$			V
V_{IL}	Low-level input voltage			$0.3 \times V_{DD}$	V
$\Delta t / \Delta V$	Input transition rise and fall rate at $\overline{MR}$ or WDI			100	ns/V
T_A	Operating free-air temperature range	−40		85	°C

7.4 Thermal Information

	THERMAL METRIC[1]	TPS382x DBV (SOT-23) 5 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	209.1	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	72.8	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	36.7	°C/W
ψ_{JT}	Junction-to-top characterization parameter	2.1	°C/W
ψ_{JB}	Junction-to-board characterization parameter	35.8	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, SPRA953.

7.5 Electrical Characteristics

over operating junction temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OH} High-level output voltage	$\overline{RESET}$	TPS382x-25	V_{DD} = V_{IT-} + 0.2 V, I_{OH} = −20 µA		0.8 × V_{DD}		V
		TPS382x-30 TPS382x-33 TPS382xA-33	V_{DD} = V_{IT-} + 0.2 V, I_{OH} = −30 µA				
		TPS382x-50	V_{DD} = V_{IT-} + 0.2 V I_{OH} = −120 µA	V_{DD} − 1.5 V			
	RESET	TPS3824-25 TPS3825-25	V_{DD} ≥ 1.8 V, I_{OH} = −100 µA		0.8 × V_{DD}		
		TPS3824-30 TPS3825-30	V_{DD} ≥ 1.8 V, I_{OH} = −150 µA				
		TPS3824-33 TPS3825-33					
		TPS3824-50 TPS3825-50					
V_{OL} Low-level output voltage	RESET	TPS3824-25 TPS3825-25	V_{DD} = V_{IT-} + 0.2 V, I_{OL} = 1 mA			0.4	V
		TPS3824-30 TPS3825-30	V_{DD} = V_{IT-} + 0.2 V, I_{OL} = 1.2 mA				
		TPS3824-33 TPS3825-33					
		TPS3824-50 TPS3825-50	V_{DD} = V_{IT-} + 0.2 V, I_{OL} = 3 mA				
	$\overline{RESET}$	TPS382x-25	V_{DD} = V_{IT-} − 0.2 V, I_{OL} = 1 mA			0.4	
		TPS382x-30					
		TPS382x-33 TPS382xA-33	V_{DD} = V_{IT-} − 0.2 V, I_{OL} = 1.2 mA				
		TPS382x-50	V_{DD} = V_{IT-} − 0.2 V, I_{OL} = 3 mA				
Power-up reset voltage[1]			V_{DD} ≥ 1.1 V, I_{OL} = 20 µA			0.4	V
V_{IT-} Negative-going input threshold voltage [2]		TPS382x-25	T_A = 0°C to 85°C	2.21	2.25	2.30	V
		TPS382x-30		2.59	2.63	2.69	
		TPS382x-33 TPS382xA-33		2.88	2.93	3	
		TPS382x-50		4.49	4.55	4.64	
		TPS382x-25	T_A = −40°C to 85°C	2.20	2.25	2.30	
		TPS382x-30		2.57	2.63	2.69	
		TPS382x-33 TPS382xA-33		2.86	2.93	3	
		TPS382x-50		4.46	4.55	4.64	
V_{hys} Hysteresis at V_{DD} input		TPS382x-25			30		mV
		TPS382x-30					
		TPS382x-33 TPS382xA-33					
		TPS382x-50			50		
$I_{IH(AV)}$ Average high-level input current	WDI		WDI = V_{DD}, time average (DC = 88%)		120		µA
$I_{IL(AV)}$ Average low-level input current			WDI = 0.3 V, V_{DD} = 5.5 V time average (DC = 12%)		−15		
I_{IH} High-level input current	WDI		WDI = V_{DD}		140	190	µA
	$\overline{MR}$		$\overline{MR}$ = V_{DD} × 0.7, V_{DD} = 5.5 V		−40	−60	
I_{IL} Low-level input current	WDI		WDI = 0.3 V, V_{DD} = 5.5 V		140	190	µA
	$\overline{MR}$		$\overline{MR}$ = 0.3 V, V_{DD} = 5.5 V		−110	−160	

(1) The lowest supply voltage at which $\overline{RESET}$ becomes active. t_r, V_{DD} ≥ 15 µs/V.
(2) To ensure best stability of the threshold voltage, a bypass capacitor (ceramic, 0.1 µF) should be placed near the supply terminals.

Electrical Characteristics (continued)

over operating junction temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{OS}	Output short-circuit current[3]	$\overline{RESET}$ TPS382x-25	$V_{DD} = V_{IT,\ max} + 0.2\ V,\ V_O = 0\ V$			−400	μA
		TPS382x-30					
		TPS382x-33 TPS382xA-33					
		TPS382x-50				−800	
I_{DD}	Supply current		WDI, $\overline{MR}$, and outputs unconnected		15	25	μA
	Internal pullup resistor at $\overline{MR}$				52		kΩ
C_i	Input capacitance at $\overline{MR}$, WDI		$V_I = 0\ V$ to 5.5 V			5	pF

(3) The $\overline{RESET}$ short-circuit current is the maximum pullup current when $\overline{RESET}$ is driven low by a microprocessor bidirectional reset pin.

7.6 Timing Requirements

At $R_L = 1\ M\Omega$, $C_L = 50\ pF$, and $T_J = 25°C$, unless otherwise noted.

				MIN	TYP	MAX	UNIT
t_w	Pulse width	at V_{DD}	$V_{DD} = V_{IT–} + 0.2\ V,\ V_{DD} = V_{IT–} − 0.2\ V$	6			μs
		at $\overline{MR}$	$V_{DD} \geq V_{IT–} + 0.2\ V,\ V_{IL} = 0.3 \times V_{DD},\ V_{IH} = 0.7 \times V_{DD}$	1			μs
		at WDI	$V_{DD} \geq V_{IT–} + 0.2\ V,\ V_{IL} = 0.3 \times V_{DD},\ V_{IH} = 0.7 \times V_{DD}$	100			ns

7.7 Switching Characteristics

At $R_L = 1\ M\Omega$, $C_L = 50\ pF$, and $T_J = 25°C$, unless otherwise noted.

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{tout}	Watchdog time out	TPS3820	$V_{DD} \geq V_{IT–} + 0.2\ V$ See Figure 1	112	200	300	ms
		TPS3823/4/8, TPS3823A		0.9	1.6	2.5	s
t_d	Delay time	TPS3820	$V_{DD} \geq V_{IT–} + 0.2\ V$ See Figure 1	15	25	37	ms
		TPS3823/4/5/8, TPS3823A		120	200	300	ms
t_{PHL}	Propagation (delay) time, high-to-low-level output	$\overline{MR}$ to $\overline{RESET}$ delay (TPS3820/3/5/8, TPS3823A)	$V_{DD} \geq V_{IT–} + 0.2\ V,\ V_{IL} = 0.3 \times V_{DD},\ V_{IH} = 0.7 \times V_{DD}$			0.1	μs
		V_{DD} to $\overline{RESET}$ delay	$V_{IL} = V_{IT–} − 0.2\ V,\ V_{IH} = V_{IT–} + 0.2\ V$			25	
t_{PLH}	Propagation (delay) time, low-to-high-level output	$\overline{MR}$ to RESET delay (TPS3824/5)	$V_{DD} \geq V_{IT–} + 0.2\ V,\ V_{IL} = 0.3 \times V_{DD},\ V_{IH} = 0.7 \times V_{DD}$			0.1	μs
		V_{DD} to RESET delay (TPS3824/5)	$V_{IL} = V_{IT–} − 0.2\ V,\ V_{IH} = V_{IT–} + 0.2\ V$			25	
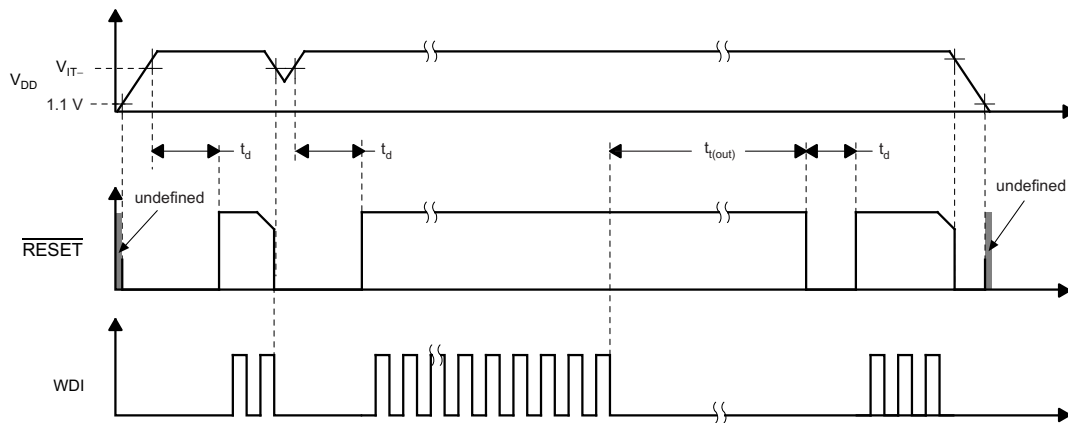
Figure 1. Timing Diagram

7.8 Typical Characteristics
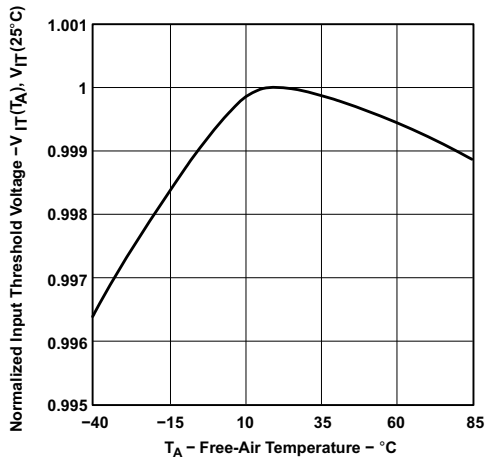
Figure 2. Normalized Input Threshold Voltage vs Free-Air Temperature at V_{DD}
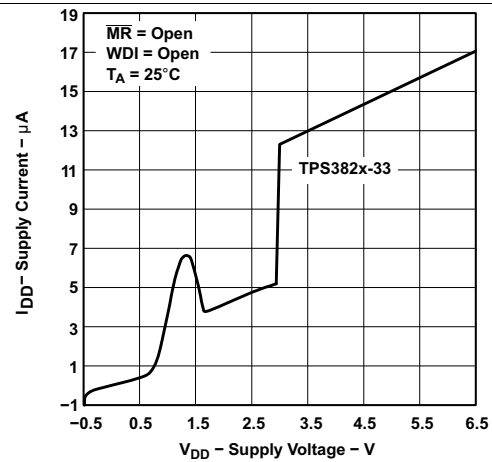
Figure 3. Supply Current vs Supply Voltage
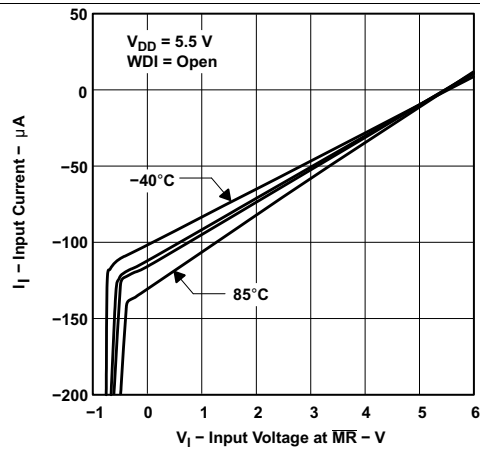
Figure 4. Input Current vs Input Voltage at $\overline{MR}$
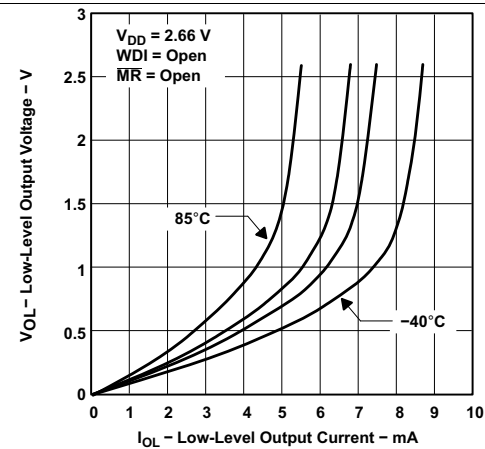
Figure 5. Low-Level Output Voltage vs Low-Level Output Current
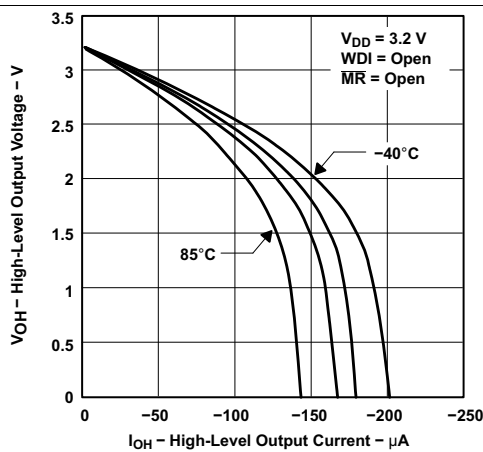
Figure 6. High-Level Output Voltage vs High-Level Output Current
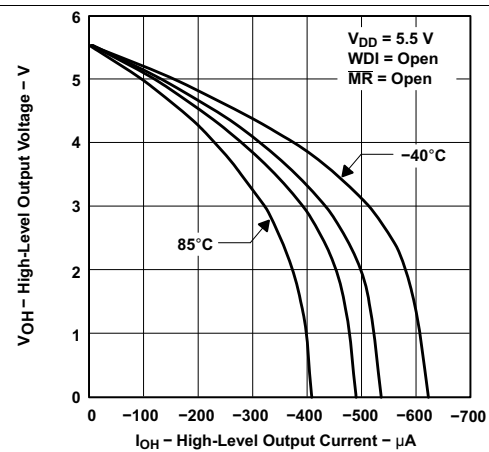
Figure 7. High-Level Output Voltage vs High-Level Output Current

Product Folder Links: *TPS3820 TPS3823 TPS3824 TPS3825 TPS3828*

Typical Characteristics (continued)
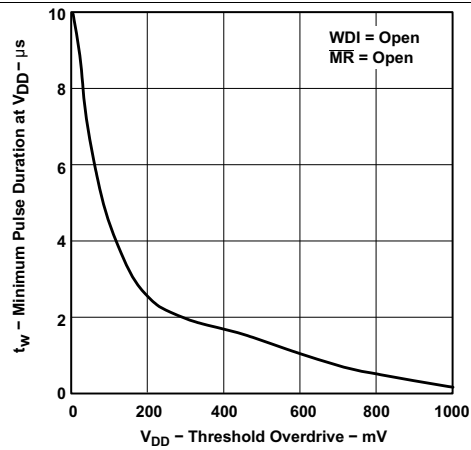
Figure 8. Minimum Pulse Duration at V_{DD} vs V_{DD} Threshold Overdrive

8 Detailed Description

8.1 Overview

The TPS382x family of supervisors provide circuit initialization and timing supervision. Optional configurations include devices with active-high and active-low output signals (TPS3824/5), devices with a watchdog timer (TPS3820/3/4/8), and devices with manual reset ($\overline{MR}$) pins (TPS3820/3/5/8). RESET asserts when the supply voltage, V_{DD}, rises above 1.1 V. For devices with active-low output logic, the device monitors V_{DD} and keeps $\overline{RESET}$ low as long as V_{DD} remains below the negative threshold voltage, V_{IT-}. For devices with active-high output logic, RESET remains high as long as V_{DD} remains below V_{IT-}. An internal timer delays the return of the output to the inactive state (high) to ensure proper system reset. The delay time, t_d, starts after V_{DD} rises above the positive threshold voltage ($V_{IT-} + V_{HYS}$). When the supply voltage drops below V_{IT-}, the output becomes active (low) again. All the devices of this family have a fixed-sense threshold voltage, V_{IT-}, set by an internal voltage divider, so no external components are required.

The TPS382x family is designed to monitor supply voltages of 2.5 V, 3 V, 3.3 V, and 5 V. The devices are available in a 5-pin SOT-23 package and are characterized for operation over a temperature range of −40°C to 85°C.

8.2 Functional Block Diagram
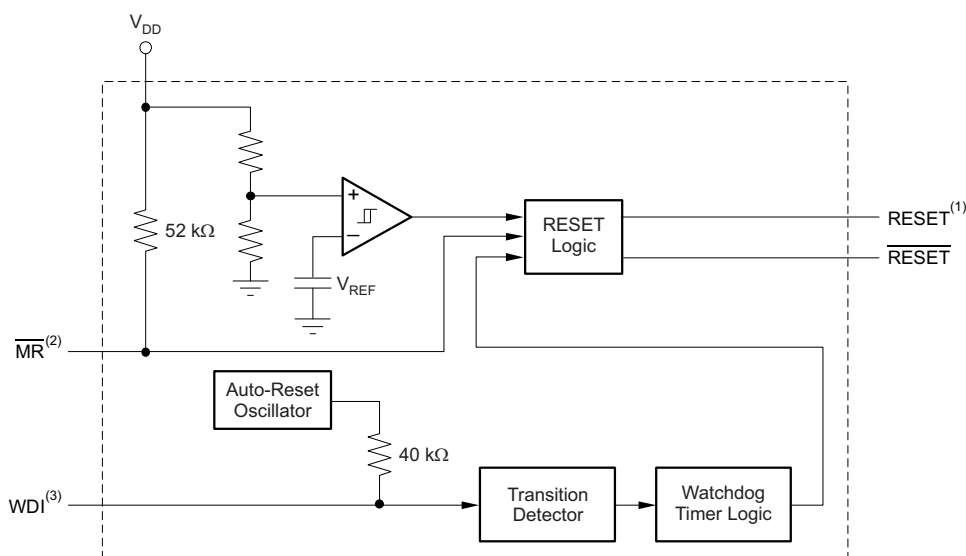
(1) TPS3824/5

(2) TPS3820/3/5/8

(3) TPS3820/3/4/8

8.3 Feature Description

8.3.1 Manual Reset ($\overline{MR}$)

The $\overline{MR}$ input allows an external logic signal from processors, logic circuits, and/or discrete sensors to force a reset signal regardless of V_{DD} with respect to V_{IT-} or the state of the watchdog timer. A low level at $\overline{MR}$ causes the reset signals to become active.

8.3.2 Active High or Active Low Output

All TPS382x devices have an active-low logic output ($\overline{RESET}$), while the TPS3824/5 devices also include an active-high logic output (RESET).

8.3.3 Push-Pull or Open-Drain Output

All TPS382x devices, except for TPS3828, have push-pull outputs. TPS3828 devices have an open-drain output.

Feature Description (continued)

8.3.4 Watchdog Timer (WDI)

TPS3820/3/4/8 devices have a watchdog timer that must be periodically triggered by either a positive or negative transition at WDI to avoid a reset signal being issued. When the supervising system fails to retrigger the watchdog circuit within the time-out interval, t_{tout}, $\overline{RESET}$ becomes active for the time period t_d. This event also reinitializes the watchdog timer.

The watchdog timer can be disabled by disconnecting the WDI pin from the system. If the WDI pin detects that it is in a high-impedance state the TPS3820/3/4/8 will generate its own WDI pulse to ensure that $\overline{RESET}$ does not assert. If this behavior is not desired place a 1kΩ resistor from WDI to ground. This resistor will help ensure that the TPS3820/3/4/8 detects that WDI is not in a high-impedance state.

In applications where the input to the WDI pin is active (transitioning high and low) when the TPS3820/3/4/8 is asserting $\overline{RESET}$, $\overline{RESET}$ will be stuck at a logic low after the input voltage returns above V_{IT-}. If the application requires that input to WDI be active when the reset signal is asserted, then either the **A** version of the device should be used or a FET to decouple the WDI signal. The **A** version does not latch the reset signal to the asserted state if a WDI pulse is received while $\overline{RESET}$ is asserted. An external FET decouples the WDI signal by disconnecting the WDI input when $\overline{RESET}$ is asserted. For more details on this, see *Decoupling WDI During Reset Event* for more details. The **A** version of the device does not need this FET but does operate in circuits that have it. Therefore, the **A** version is backwards-compatible with the non-**A** versions.

8.4 Device Functional Modes

Table 1. Function Table

INPUTS		OUTPUTS	
$\overline{MR}$ [1]	$V_{DD} > V_{IT}$	$\overline{RESET}$	RESET[2]
L	0	L	H
L	1	L	H
H	0	L	H
H	1	H	L

(1) TPS3820/3/5/8
(2) TPS3824/5

9 Application and Implementation

> **NOTE**
> Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The TPS382x family of devices are very small supervisory circuits that monitor fixed supply voltages of 2.5 V, 3 V, 3.3 V, and 5 V. The TPS382x family operates from 1.1 V to 5.5 V. Orderable options include versions with either push-pull or open-drain outputs, versions that use active-high or active-low logic for output signals, versions with a manual reset pin, and versions with a watchdog timer. See the *Device Comparison Table* for an overview of device options.

9.2 Typical Applications

9.2.1 Supply Rail Monitoring with Watchdog Time-out and 200-ms Delay

The TPS3823A can be used to monitor the supply rail for devices such as microcontrollers. The downstream device is enabled by the TPS3823A once the voltage on the supply pin (V_{DD}) is above the internal threshold voltage ($V_{IT-} + V_{HYS}$). The downstream device is disabled by the TPS3823A when V_{DD} falls below the threshold voltage minus the hysteresis voltage (V_{IT-}). The TPS3823A also issues a reset signal if the WDI input is not periodically triggered by a positive or negative transition at WDI. When the supervising system fails to retrigger the watchdog circuit within the time-out interval, t_{tout}, $\overline{RESET}$ becomes active for the time period t_d.

Some applications require a shorter reset signal than the 200 ms that most of the TPS382x family provide. In these cases, the TPS3820 is a good choice because it has a delay time of only 25 ms. If an open-drain output is needed, replace the TPS3823A with the TPS3828 (if the WDI input must be active while $\overline{RESET}$ is low, see *Decoupling WDI During Reset Event*). Figure 9 shows the TPS3823A in a typical application.
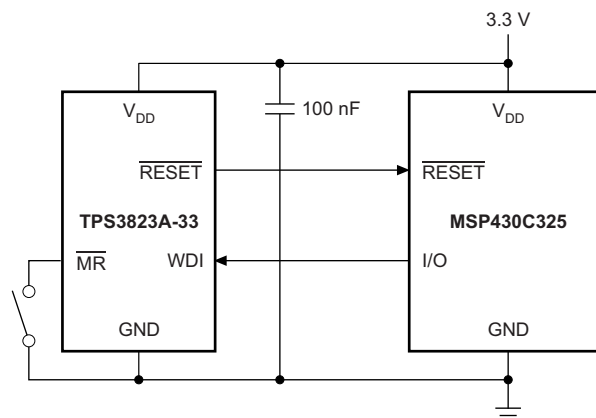
Figure 9. Supply Rail Monitoring With Watchdog Time-out

9.2.1.1 Design Requirements

The TPS3823A must drive the enable pin of a MSP430C325 using a logic-high signal to signify that the supply voltage is above the minimum operating voltage of the device and monitor the I/O pin to determine if the microcontroller is operating correctly.

Typical Applications (continued)

9.2.1.2 Detailed Design Procedure

Determine which version of the TPS382x family best suits the functional performance required.

If the input supply is noisy, include an input capacitor to help avoid unwanted changes to the reset signal.

9.2.1.3 Application Curve
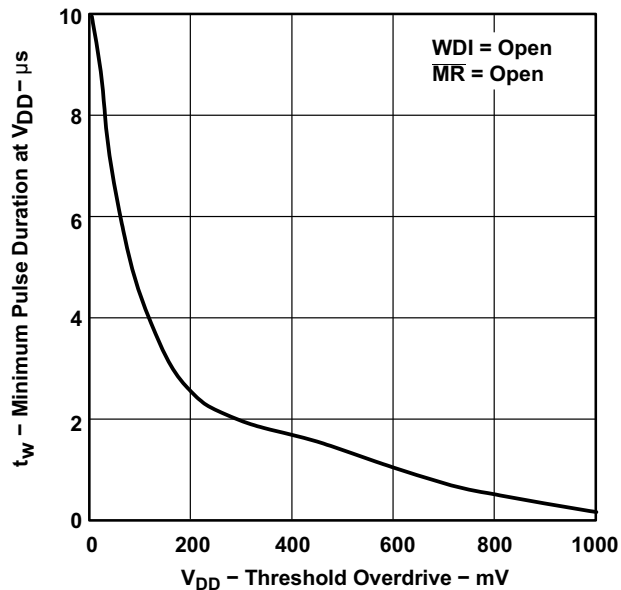
Figure 10. Minimum Pulse Duration at V_{DD} vs V_{DD} Threshold Overdrive

Typical Applications (continued)

9.2.2 Decoupling WDI During Reset Event

If the application requires that the input to WDI is active when the reset signal is asserted and the **A** version of the device cannot be used, Figure 11 shows how to decouple WDI from the active signal using an N-channel FET. The N-channel FET is placed in series with the WDI pin, with the gate of the FET connected to the RESET output.
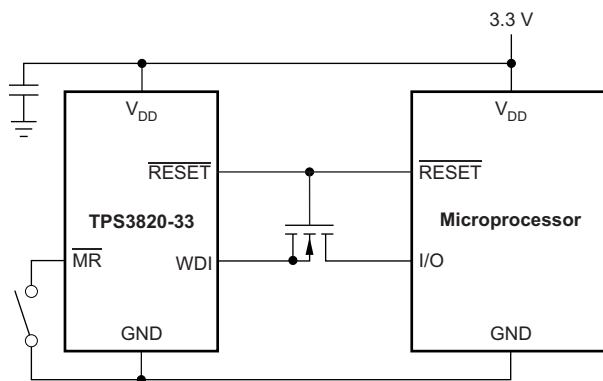
Figure 11. WDI Example

9.2.2.1 Design Requirements

The TPS3820 must drive the enable pin of a microprocessor using a logic-high signal to signify that the supply voltage is above the minimum operating voltage of the device and monitor the I/O pin to determine if the microcontroller is operating correctly. The reset signal delay time should be greater than 10 ms but less than 50 ms to achieve the desired behavior.

9.2.2.2 Detailed Design Procedure

Determine which version of the TPS3820 is best suited for monitoring the supply voltage.

If the input supply is noisy, include an input capacitor to help avoid unwanted changes to the reset signal.

9.2.2.3 Application Curve
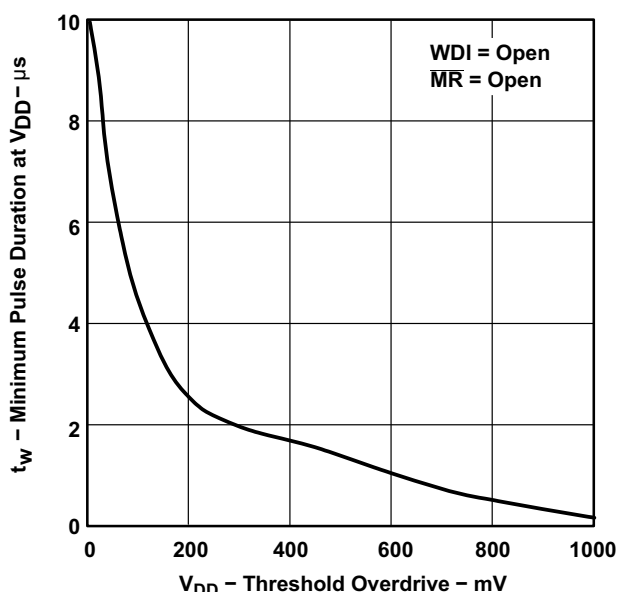
Figure 12. Minimum Pulse Duration at V_{DD} vs V_{DD} Threshold Overdrive

Product Folder Links: *TPS3820 TPS3823 TPS3824 TPS3825 TPS3828*

10 Power Supply Recommendations

These devices are designed to operate from an input supply with a voltage range from 1.1 V to 5.5 V. Though not required, it is good analog design practice to place a 0.1-µF ceramic capacitor close to the V_{DD} pin if the input supply is noisy.

11 Layout

11.1 Layout Guidelines

Follow these guidelines to lay out the printed-circuit-board (PCB) that is used for the TPS382x family of devices.
- Place the V_{DD} decoupling capacitor (C_{VDD}) close to the device.
- Avoid using long traces for the V_{DD} supply node. The V_{DD} capacitor (C_{VDD}), along with parasitic inductance from the supply to the capacitor, can form an LC tank and create ringing with peak voltages above the maximum V_{DD} voltage.

11.2 Layout Example
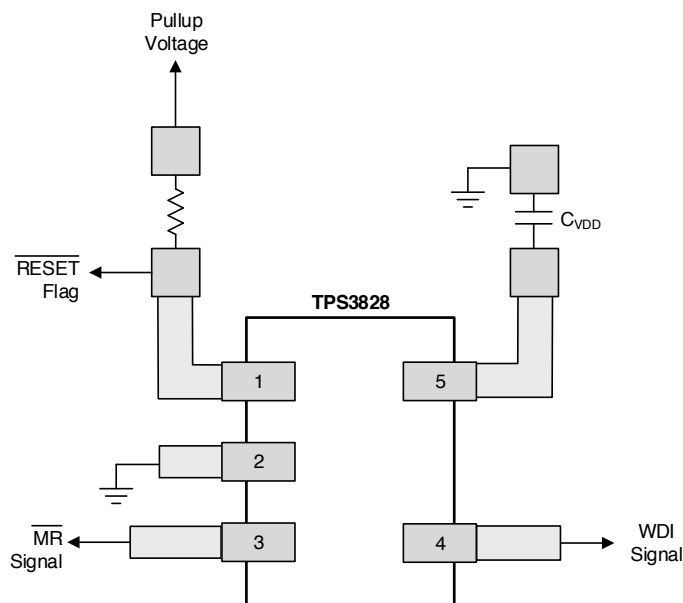
Figure 13. Example Layout (DBV Package)

12 Device and Documentation Support

12.1 Device Support

12.1.1 Development Support

12.1.1.1 Spice Models

Computer simulation of circuit performance using SPICE is often useful when analyzing the performance of analog circuits and systems. A SPICE model for the TPS382x is available through the product folders under *Tools & Software*.

12.1.2 Device Nomenclature

Table 2. Ordering Information[1]

ORDERABLE DEVICE NAME[2] [3]		THRESHOLD VOLTAGE[4]	MARKING
TPS3820-33DBVT	TPS3820-33DBVR	2.93 V	PDEI
TPS3820-50DBVT	TPS3820-50DBVR	4.55 V	PDDI
TPS3823-25DBVT	TPS3823-25DBVR	2.25 V	PAPI
TPS3823-30DBVT	TPS3823-30DBVR	2.63 V	PAQI
TPS3823-33DBVT	TPS3823-33DBVR	2.93 V	PARI
TPS3823-50DBVT	TPS3823-50DBVR	4.55 V	PASI
TPS3824-25DBVT	TPS3824-25DBVR	2.25 V	PATI
TPS3824-30DBVT	TPS3824-30DBVR	2.63 V	PAUI
TPS3824-33DBVT	TPS3824-33DBVR	2.93 V	PAVI
TPS3824-50DBVT	TPS3824-50DBVR	4.55 V	PAWI
TPS3825-33DBVT	TPS3825-33DBVR	2.93 V	PDGI
TPS3825-50DBVT	TPS3825-50DBVR	4.55 V	PDFI
TPS3828-33DBVT	TPS3828-33DBVR	2.93 V	PDII
TPS3828-50DBVT	TPS3828-50DBVR	4.55 V	PDHI
TPS3823A-33DBVT	TPS3823A-33DBVR	2.93 V	PYPI

(1) For the most current package and ordering information see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.
(2) The DBVT package indicates tape and reel of 250 parts.
(3) The DBVR package indicates tape and reel of 3000 parts.
(4) For other threshold voltage versions, contact the local TI sales office.

12.2 Documentation Support

12.2.1 Related Documentation

For related documentation see the following:
• *Disabling the Watchdog Timer for TI's Family of Supervisors*, SLVA145

12.3 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 3. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
TPS3820	Click here	Click here	Click here	Click here	Click here
TPS3823	Click here	Click here	Click here	Click here	Click here
TPS3824	Click here	Click here	Click here	Click here	Click here
TPS3825	Click here	Click here	Click here	Click here	Click here
TPS3828	Click here	Click here	Click here	Click here	Click here

12.4 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community.* Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.5 Trademarks

E2E is a trademark of Texas Instruments.
All other trademarks are the property of their respective owners.

12.6 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.7 Glossary

SLYZ022 — *TI Glossary*.
This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS3820-33DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDEI	Samples
TPS3820-33DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDEI	Samples
TPS3820-33DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDEI	Samples
TPS3820-33DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDEI	Samples
TPS3820-50DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDDI	Samples
TPS3820-50DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDDI	Samples
TPS3820-50DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDDI	Samples
TPS3820-50DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDDI	Samples
TPS3823-25DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PAPI	Samples
TPS3823-25DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PAPI	Samples
TPS3823-25DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAPI	Samples
TPS3823-25DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAPI	Samples
TPS3823-30DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PAQI	Samples
TPS3823-30DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PAQI	Samples
TPS3823-30DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAQI	Samples
TPS3823-30DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAQI	Samples
TPS3823-33DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PARI	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS3823-33DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PARI	Samples
TPS3823-33DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PARI	Samples
TPS3823-33DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PARI	Samples
TPS3823-50DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PASI	Samples
TPS3823-50DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PASI	Samples
TPS3823-50DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PASI	Samples
TPS3823-50DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PASI	Samples
TPS3823A-33DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PYPI	Samples
TPS3823A-33DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PYPI	Samples
TPS3824-25DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PATI	Samples
TPS3824-25DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PATI	Samples
TPS3824-25DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PATI	Samples
TPS3824-25DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PATI	Samples
TPS3824-30DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PAUI	Samples
TPS3824-30DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PAUI	Samples
TPS3824-30DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAUI	Samples
TPS3824-30DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAUI	Samples
TPS3824-33DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PAVI	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS3824-33DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PAVI	Samples
TPS3824-33DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAVI	Samples
TPS3824-33DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAVI	Samples
TPS3824-50DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PAWI	Samples
TPS3824-50DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PAWI	Samples
TPS3824-50DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAWI	Samples
TPS3824-50DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAWI	Samples
TPS3825-33DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDGI	Samples
TPS3825-33DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDGI	Samples
TPS3825-33DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDGI	Samples
TPS3825-33DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDGI	Samples
TPS3825-50DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDFI	Samples
TPS3825-50DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDFI	Samples
TPS3825-50DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDFI	Samples
TPS3825-50DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDFI	Samples
TPS3828-33DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDII	Samples
TPS3828-33DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDII	Samples
TPS3828-33DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDII	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS3828-33DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDII	Samples
TPS3828-50DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDHI	Samples
TPS3828-50DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDHI	Samples
TPS3828-50DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDHI	Samples
TPS3828-50DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDHI	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TPS3820-33, TPS3820-50, TPS3823-25, TPS3823-30, TPS3823-33, TPS3823-50, TPS3824-25, TPS3824-30, TPS3824-33, TPS3824-50, TPS3825-33, TPS3825-50, TPS3828-33, TPS3828-50 :
- Automotive: TPS3820-33-Q1, TPS3820-50-Q1, TPS3823-25-Q1, TPS3823-30-Q1, TPS3823-33-Q1, TPS3823-50-Q1, TPS3824-25-Q1, TPS3824-30-Q1, TPS3824-33-Q1, TPS3824-50-Q1, TPS3825-33-Q1, TPS3825-50-Q1, TPS3828-33-Q1, TPS3828-50-Q1

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3820-33DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3820-33DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3820-50DBVR	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3820-50DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3820-50DBVT	SOT-23	DBV	5	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3820-50DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3823-25DBVR	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3823-25DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3823-25DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3823-25DBVT	SOT-23	DBV	5	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3823-30DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3823-30DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3823-33DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3823-33DBVT	SOT-23	DBV	5	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3823-50DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3823-50DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3823A-33DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3823A-33DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3824-25DBVR	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3824-25DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3824-25DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3824-25DBVT	SOT-23	DBV	5	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3824-30DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3824-30DBVR	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3824-30DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3824-30DBVT	SOT-23	DBV	5	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3824-33DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3824-33DBVT	SOT-23	DBV	5	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3824-50DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3824-50DBVT	SOT-23	DBV	5	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3824-50DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3825-33DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3825-33DBVT	SOT-23	DBV	5	250	178.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
TPS3825-50DBVR	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3825-50DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3825-50DBVT	SOT-23	DBV	5	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS3828-33DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3828-33DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3828-50DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3828-50DBVT	SOT-23	DBV	5	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3

![Texas Instruments logo] **PACKAGE MATERIALS INFORMATION**

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3820-33DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3820-33DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS3820-50DBVR	SOT-23	DBV	5	3000	203.0	203.0	35.0
TPS3820-50DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3820-50DBVT	SOT-23	DBV	5	250	203.0	203.0	35.0
TPS3820-50DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS3823-25DBVR	SOT-23	DBV	5	3000	203.0	203.0	35.0
TPS3823-25DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3823-25DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS3823-25DBVT	SOT-23	DBV	5	250	203.0	203.0	35.0
TPS3823-30DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3823-30DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS3823-33DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3823-33DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS3823-50DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3823-50DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS3823A-33DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3823A-33DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS3824-25DBVR	SOT-23	DBV	5	3000	203.0	203.0	35.0
TPS3824-25DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0

PACKAGE MATERIALS INFORMATION

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3824-25DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS3824-25DBVT	SOT-23	DBV	5	250	203.0	203.0	35.0
TPS3824-30DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3824-30DBVR	SOT-23	DBV	5	3000	203.0	203.0	35.0
TPS3824-30DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS3824-30DBVT	SOT-23	DBV	5	250	203.0	203.0	35.0
TPS3824-33DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3824-33DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS3824-50DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3824-50DBVT	SOT-23	DBV	5	250	203.0	203.0	35.0
TPS3824-50DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS3825-33DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3825-33DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS3825-50DBVR	SOT-23	DBV	5	3000	203.0	203.0	35.0
TPS3825-50DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3825-50DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS3828-33DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3828-33DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS3828-50DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3828-50DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0

DBV (R−PDSO−G5)   PLASTIC SMALL−OUTLINE PACKAGE
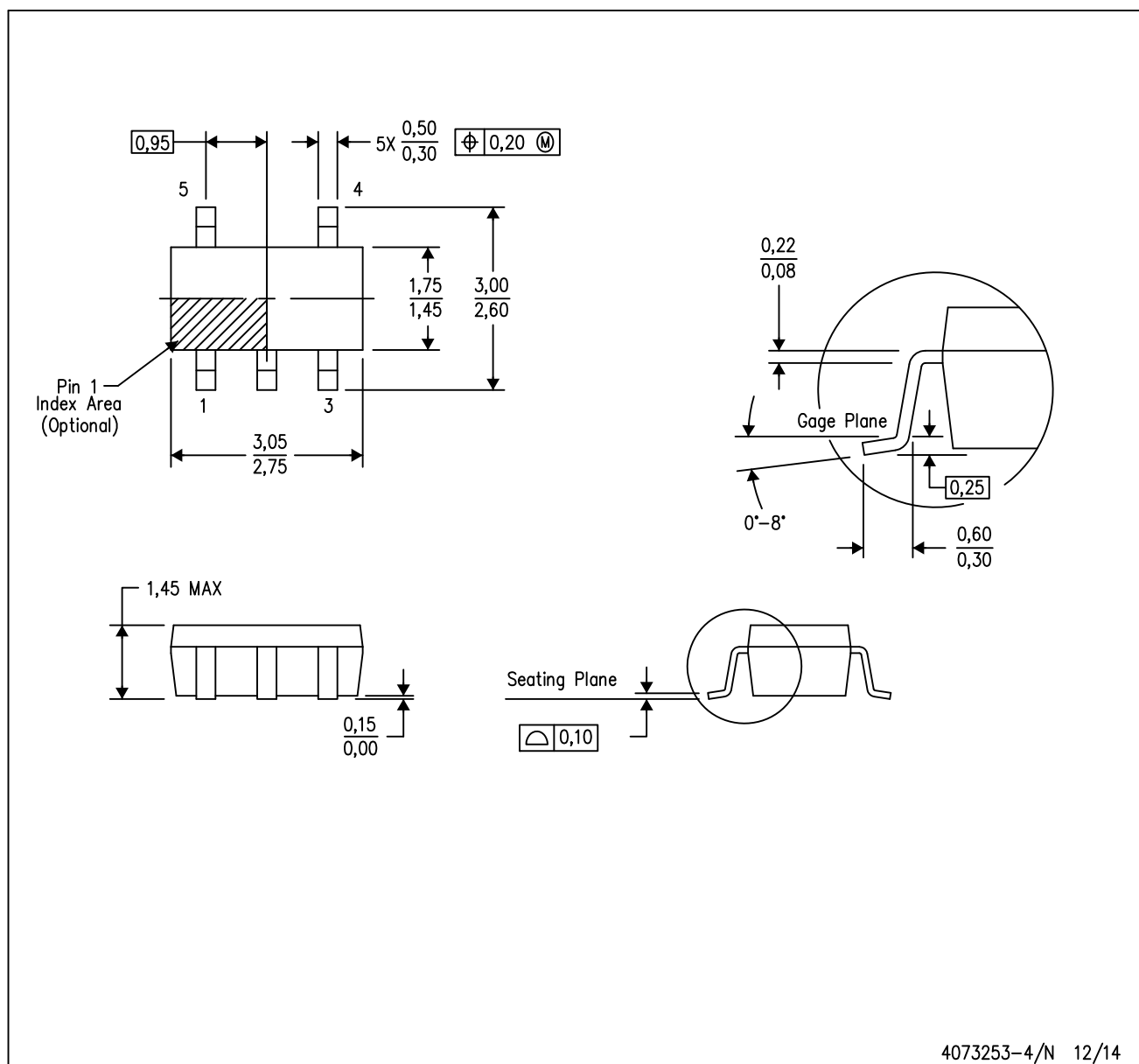
0,95

5X $\frac{0,50}{0,30}$ ⊕ |0,20 Ⓜ|

5   4

$\frac{1,75}{1,45}$ $\frac{3,00}{2,60}$

Pin 1
Index Area
(Optional)

1   3

$\frac{3,05}{2,75}$

$\frac{0,22}{0,08}$

Gage Plane

0°−8°

|0,25|

$\frac{0,60}{0,30}$

1,45 MAX

$\frac{0,15}{0,00}$

Seating Plane

⌒ |0,10|

4073253−4/N 12/14

NOTES: A. All linear dimensions are in millimeters.
        B. This drawing is subject to change without notice.
        C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
        D. Falls within JEDEC MO−178 Variation AA.

DBV (R-PDSO-G5)   PLASTIC SMALL OUTLINE
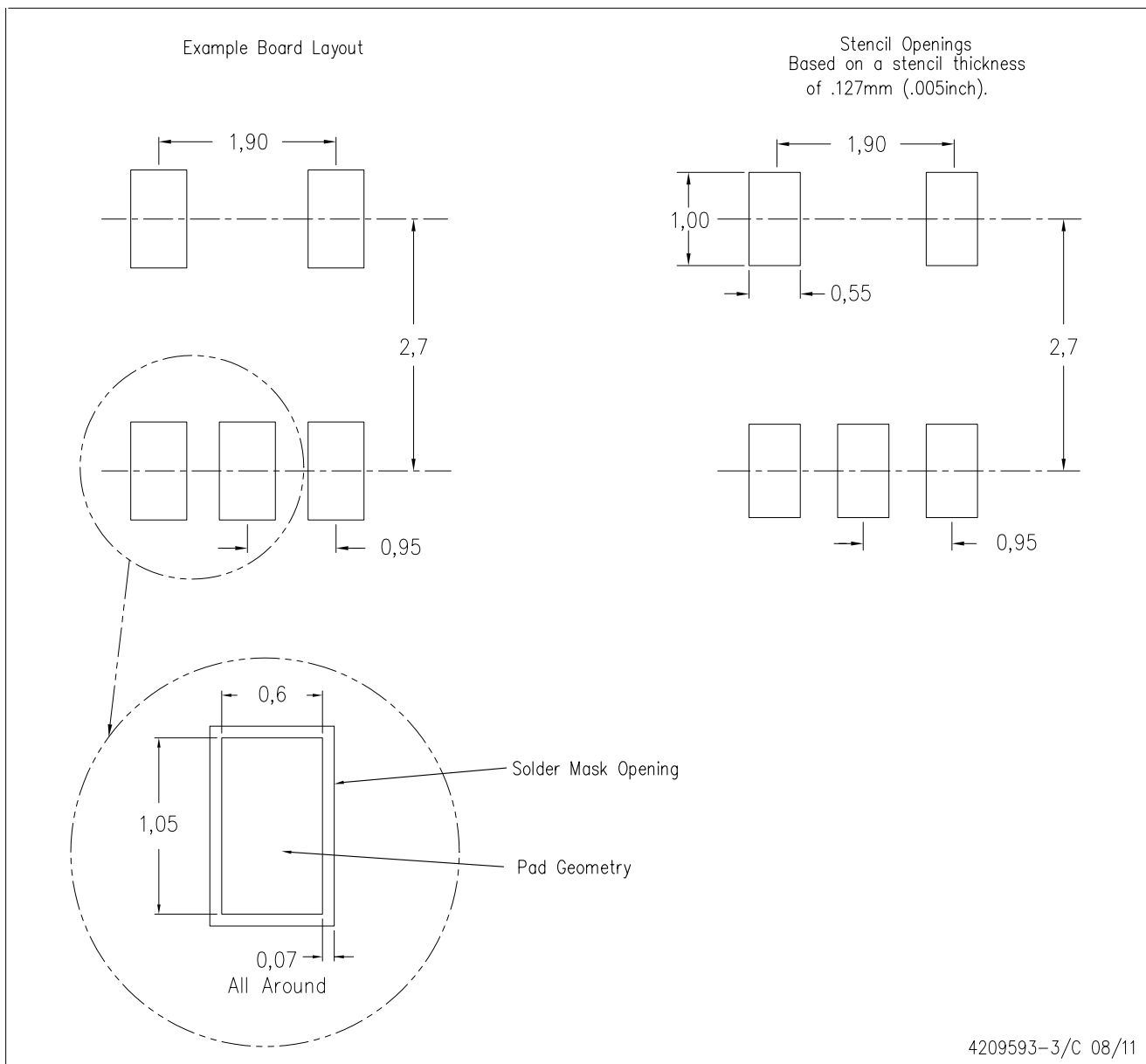
Example Board Layout

Stencil Openings
Based on a stencil thickness
of .127mm (.005inch).

1,90

1,90

1,00

0,55

2,7

2,7

0,95

0,95

0,6

Solder Mask Opening

1,05

Pad Geometry

0,07
All Around

4209593-3/C 08/11

NOTES: A.   All linear dimensions are in millimeters.
         B.   This drawing is subject to change without notice.
         C.   Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
         D.   Publication IPC-7351 is recommended for alternate designs.
         E.   Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
              contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric
              metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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